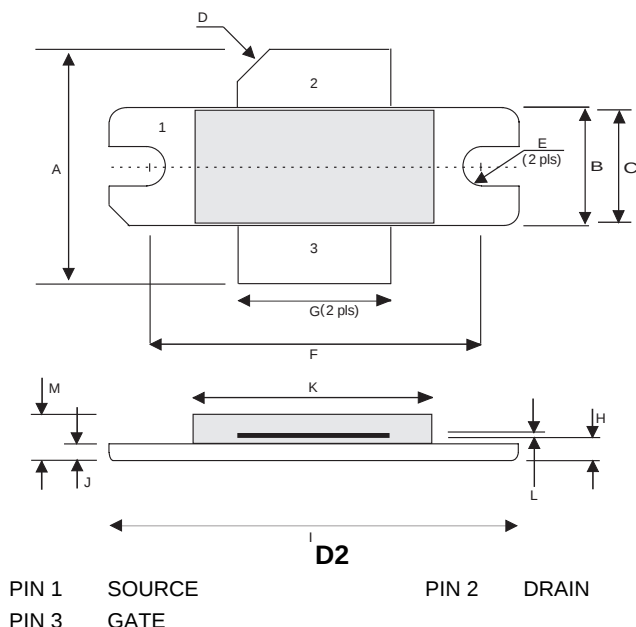


MECHANICAL DATA



PIN 1 SOURCE
PIN 3 GATE
PIN 2 DRAIN

DIM	Millimetres	Tol.	Inches	Tol.
A	19.43	0.13	0.765	0.005
B	9.78	0.13	0.385	0.005
C	9.40	0.10	0.370	0.004
D	45°	5°	45°	5°
E	1.63R	0.13	0.064R	0.005
F	27.94	0.13	1.100	0.005
G	12.70	0.13	0.500	0.005
H	1.57	0.13	0.062	0.005
I	34.04	0.13	1.340	0.005
J	1.01	0.13	0.040	0.005
K	19.94	0.25	0.785	0.009
L	0.10	0.25	0.004	0.002
M	4.24	0.25	0.167	0.01

GOLD METALLISED MULTI-PURPOSE SILICON DMOS RF FET 150W – 28V – 175MHz SINGLE ENDED

FEATURES

- SUITABLE FOR BROAD BAND APPLICATIONS
- SIMPLE BIAS CIRCUITS
- ULTRA-LOW THERMAL RESISTANCE
- BeO FREE
- LOW C_{rss}
- HIGH GAIN - 15 dB MINIMUM

APPLICATIONS

- HF/VHF/UHF COMMUNICATIONS
from 1 MHz to 200 MHz

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

P_D	Power Dissipation	438W (219W -A Version)
BV_{DSS}	Drain – Source Breakdown Voltage	70V
BV_{GSS}	Gate – Source Breakdown Voltage	$\pm 20V$
$I_{D(sat)}$	Drain Current	30A
T_{stg}	Storage Temperature	-65 to $150^{\circ}C$
T_j	Maximum Operating Junction Temperature	$200^{\circ}C$

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}C$ unless otherwise stated)

Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BV_{DSS} Drain-Source Breakdown Voltage	$V_{GS} = 0$ $I_D = 100mA$	70			V
I_{DSS} Zero Gate Voltage Drain Current	$V_{DS} = 28V$ $V_{GS} = 0$			6	mA
I_{GSS} Gate Leakage Current	$V_{GS} = 20V$ $V_{DS} = 0$			1	μA
$V_{GS(th)}$ Gate Threshold Voltage*	$I_D = 10mA$ $V_{DS} = V_{GS}$	1		7	V
g_{fs} Forward Transconductance*	$V_{DS} = 10V$ $I_D = 6A$	4.8			S
G_{PS} Common Source Power Gain	$P_O = 150W$	15			dB
η Drain Efficiency	$V_{DS} = 28V$ $I_{DQ} = 1.2A$	50			%
VSWR Load Mismatch Tolerance	$f = 175MHz$	20:1			—
C_{iss} Input Capacitance	$V_{DS} = 0V$ $V_{GS} = -5V$ $f = 1MHz$			360	pF
C_{oss} Output Capacitance	$V_{DS} = 28V$ $V_{GS} = 0$ $f = 1MHz$			180	pF
C_{rss} Reverse Transfer Capacitance	$V_{DS} = 28V$ $V_{GS} = 0$ $f = 1MHz$			15	pF

* Pulse Test: Pulse Duration = 300 μs , Duty Cycle $\leq 2\%$

THERMAL DATA

$R_{THj-case}$	Thermal Resistance Junction – Case	Max. 0.4 $^{\circ}C / W$ 0.8 $^{\circ}C / W$ -A Version
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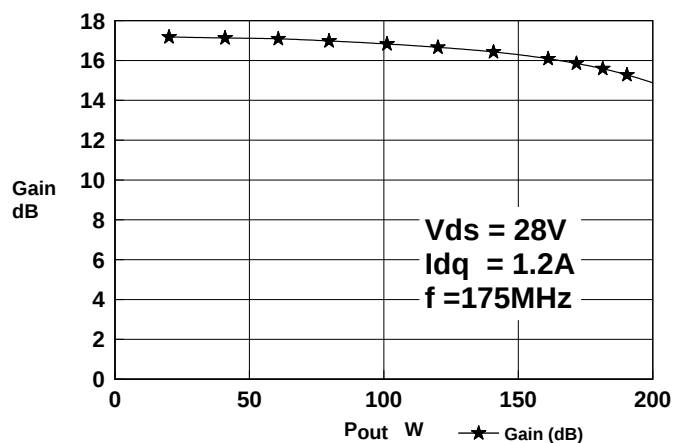


Figure 1.
Gain vs. Output Power

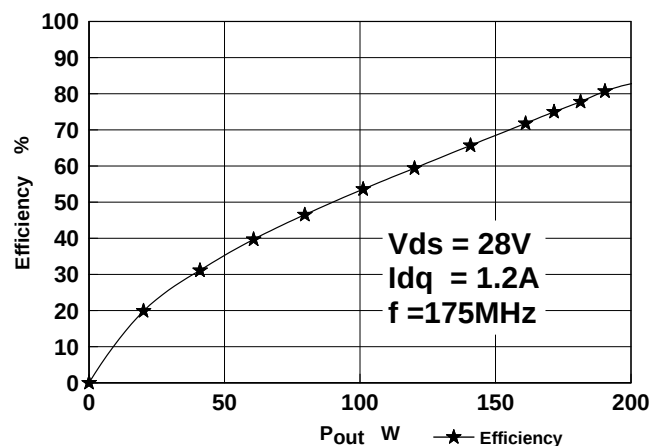


Figure 2.
Efficiency vs. Output Power

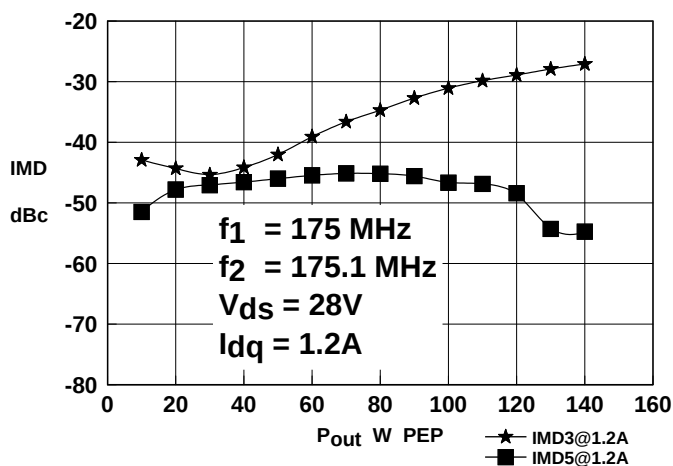


Figure 3.
IMD vs Output Power

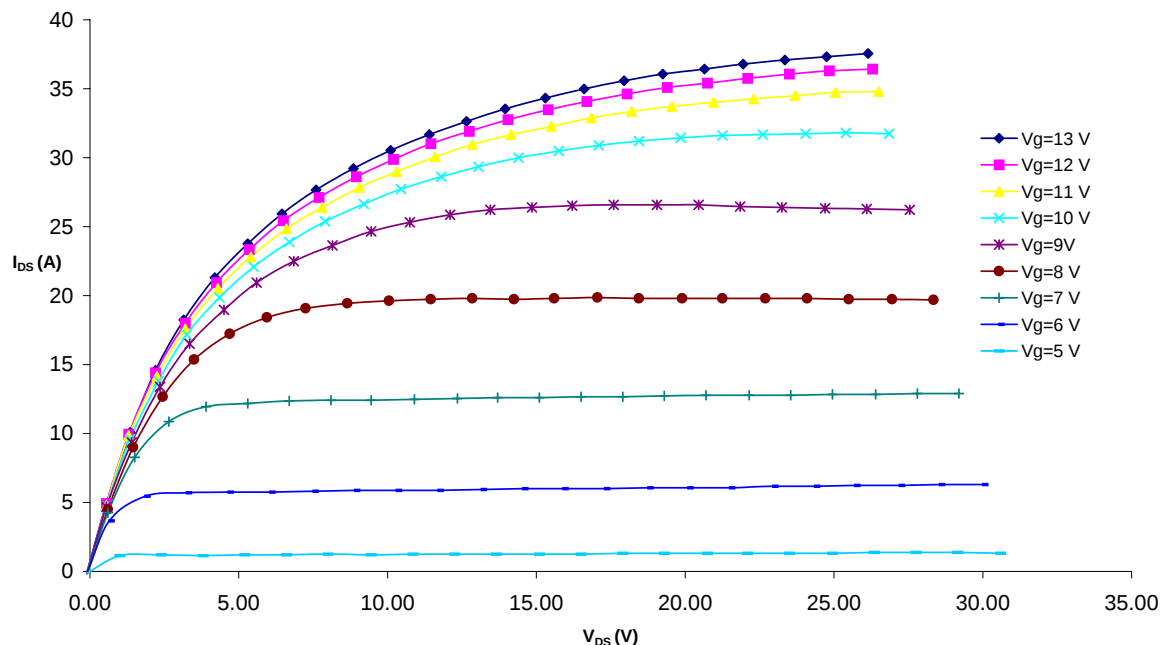


Figure 4 – Typical IV Characteristics.

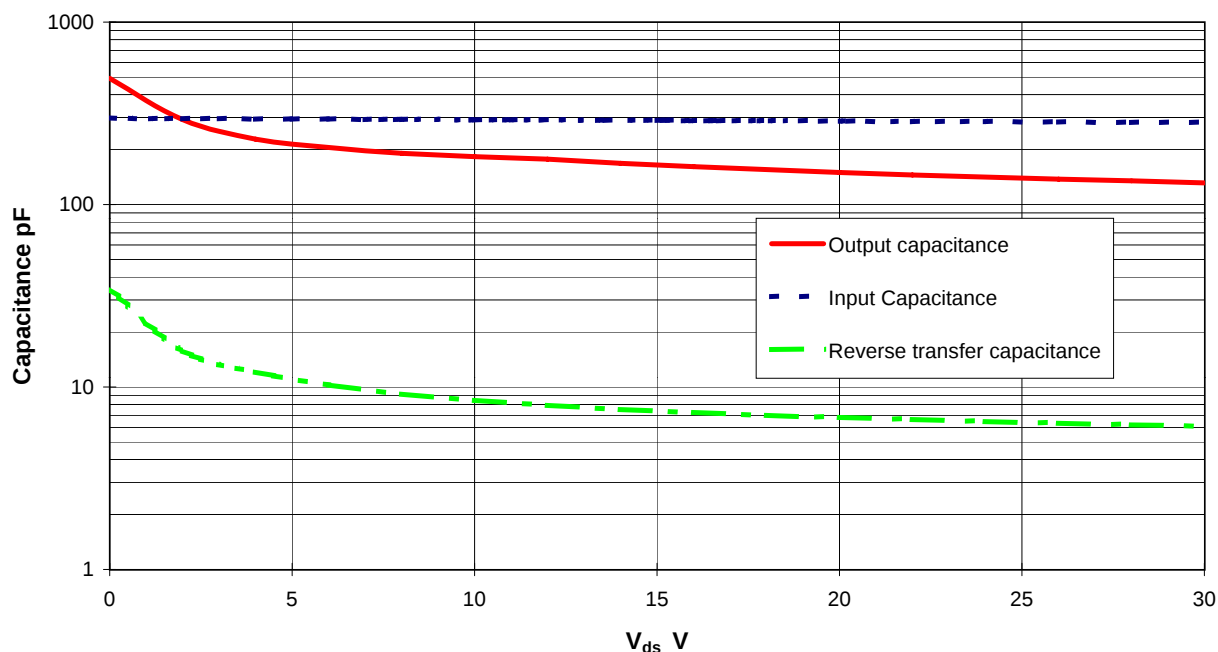


Figure 5 – Typical CV Characteristics.



All microstrip lines $W = 5\text{mm}$

T3 20mm

L2 11 turns 19swg enamelled copper wire on Fair-Rite FT82 ferrite core